

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A11105PDRVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A11105PDRVR	NIPDAU	Level-1-260C-UNLIM	TI Semiconductor	DRV 6	2x2x0.75	11.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.024537	100	1000000	0.206232	2062
Sub-Total			0.024537	100	1000000	0.206232	2062
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.141024	80	800000	1.185297	11853
Thermoplastics	Epoxy	85954-11-6	0.035256	20	200000	0.296324	2963
Sub-Total			0.17628	100	1000000	1.481622	14816
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.959027	97.519997	975200	58.49016	584902
Copper and Its Alloys	Iron	7439-89-6	0.164128	2.3	23000	1.379485	13795
Copper and Its Alloys	Phosphorus	7723-14-0	0.002141	0.030003	300	0.017995	180
Zinc and Its Alloys	Zinc	7440-66-6	0.010704	0.15	1500	0.089966	900
Sub-Total			7.136	100	1000000	59.977606	599776
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.207362	95.120183	951202	1.742864	17429
Precious Metals	Gold	7440-57-5	0.0017	0.779817	7798	0.014288	143
Precious Metals	Palladium	7440-05-3	0.008938	4.1	41000	0.075123	751
Sub-Total			0.218	100	1000000	1.832276	18323
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	3.478577	87.999987	880000	29.237209	292372
Other Organic Materials	Chlorine	7782-50-5	0.00004	0.001012	10	0.000336	3
Other Plastics and Rubber	Carbon Black	1333-86-4	0.011859	0.300005	3000	0.099674	997
Thermoplastics	Epoxy	85954-11-6	0.462453	11.698996	116990	3.886887	38869
Sub-Total			3.952929	100	1000000	33.224106	332241
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.390028	100	1000000	3.278159	32782
Sub-Total			0.390028	100	1000000	3.278159	32782
Total			11.897774			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.